

MSP430FR4xx and MSP430FR2xx Bootloader (BSL)

All information from previous versions of the *MSP430FR4xx and MSP430FR2xx Bootloader (BSL) User's Guide* and the *MSP430FR5xx and MSP430FR6xx Bootloader (BSL) User's Guide* has been consolidated into the [MSP430™ FRAM Devices Bootloader \(BSL\) User's Guide](#).

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